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| 光电LOGO.jpg | **2023第十七届北京国际半导体展览会(CIOE EXPO)** | | | | | | | | | | | | | | | **参展申请表|合同表**  **APPLICATION FORM / AGREEMENT** | | | | | | | | | | | | |
| **The 17th Beijing International Semiconductor Exhibition 2023（CIOE EXPO）** | | | | | | | | | | | | | | |
| 2023年07月05日-07日 | | | | | | | |  | | | | | | |
| 中国国际展览中心·北京朝阳 | | | | | | | | **NO. NO.** | | | | | | |
|  | | | | | | | | | | | | | | | | | | | | **NO.** | | | | | | | | |
| 请详细阅读招展书并了解相关参展规则后填写参展申请表，所有注明\*为必填项目，参展企业负责人签字并加盖公章后将此表传真至010-68683796， | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 或将此表扫描后发送电子邮件至huamaolian@263.net。组委会将以此规划展位。申请截止日期：2023年05月20日。 | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| 公司信息 | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 公司名称（中文）\* | |  | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 公司名称（英文）\* | |  | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 通信地址\* | |  | | | | | | | | | | | | | | | | 邮政编码\* | | |  | | | | | | | |
| 联系人\* | |  | | | | □先生□女士 | | 职务 | | | |  | | | | | | 电子邮件\* | | |  | | | | | | | |
| 手机号码\* | |  | | | | 区号\*| | | 电话\* | | | |  | | | | | | 传真\* | | |  | | | | | | | |
| 企业性质\* | | □国内 □合资 | | | | 单独/联合参展\* | | | | | | □单独 □联合 | | | | | | 公司网站 | | |  | | | | | | | |
|  | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 展位价格 | | | | | | | | | |  | 展品类型\*请将贵司参展展品中最主要设备类型进行勾选 | | | | | | | | | | | | | | | | | |
| **我公司确定报名参展并申请展位\*** | | | | | | | | | |  | □半导体设计、封测、制造产厂商 | | | | | | | | | | | | | | | | | |
| 室内光地价格（元人民币/㎡） | | | | | | | | | |  | □原材料：硅晶圆、硅晶片、光刻胶、光掩膜版、电子气体及特种化学气体、CMP抛光扽材料； | | | | | | | | | | | | | | | | | |
| 面积范围㎡ | 国内企业 | | | 合（外）资企业 | | | 展位尺寸(长×宽) | | |  | □生产设备：单晶炉、氧化炉、扩散设备、离子注入设备、PVD、CVD 、光刻机等 | | | | | | | | | | | | | | | | | |
| 36-72 | 1700 | | | 4000 | | |  | | |  | □封装工艺及设备：减薄机、划片机、贴片机 焊线机、塑封机、打弯设备、分选机、测试机 | | | | | | | | | | | | | | |
| 73-199 | 1530 | | | 3600 | | |  | | |  | □测试与封装配套产品：探针卡、引线键合、烧焊测试、自动化测试、激光切割及其它、研磨液，划片液、封片膜(胶)高温胶带、层压基板、 | | | | | | | | | | | | | | |
| 200-399 | 1360 | | | 3200 | | |  | | |  |
| ≥400 | 1190 | | | 2700 | | |  | | |  | □其他 | | | | | | | | | | | | | | | | | |
|  |  | | |  | | |  | | |  |  | | | | | | | |  | | |  |  | |  | | | |
| 标准展位价格（元人民币/㎡） | | | | | | | | | |  | 其他说明 | | | | | | | | | | | | | | | | | |
| 展位类型 | 国内企业 | | | 合（外）资企业 | | | 展位尺寸(长×宽) | | |  | **IMG_257** | | 申请展位合同签订五个工作日内将展位费全款汇入展会组委会指定账户 | | | | | | | | | | | | | | | |
| 9㎡精装修展位 | 23800 | | | 40000 | | | 3m×3m=9㎡ | | |  |  | | 参展单位均须遵守本会及展馆的各项有关规定，详见《参展商手册》  参展单位自行转让展位或展示与展品范围不相符产品，本会将取消其参展资格，所缴费用概不退还 签合同的单位未按合同规定日期付款，承办单位有权取消展位。 参展单位在交付费用后放弃参展，所交费用不予退回 | | | | | | | | | | | | | | | |
| 9㎡标准展位 | 16800 | | | 40000 | | | 3m×3m=9㎡ | | |  |
|  |  | | | 注：双开口展位加收20% | | | | | |  |
|  |  | | |  | | |  | | |  |
| 展位说明 | | | | | | | | | |  |
| ★光地展位：指除室内标准展位以外所有展位均为光地，此展位不提供任何装饰及电源，参展商须自行设计并搭建展台。 ★展位规划：标准展位的申请主要是依据展品类型及报名先后顺序进行划分。特装展位的申请主要是依据展品类型、报名顺序、参展尺寸、设备重量等多因素进行划分。 ★室内光地展位起租面积为36㎡，室外光地展位起租面积为100㎡。 ★参展商在获得展位后不得将展位全部或部分转租、转让给第三方。 ★展馆地面承重5000Kg/㎡。进货门高6m，宽6m。 ★展位位置及参展面积须经参展商与组委会共同确认后方有效。 | | | | | | | | | |  | 展位费用\*IMG_258 | | | | | | | | | | | | | | | | | |
|  | 展位号 | | | | 面积㎡ | | 费用标准 | | | 费用小计 | | | | | | | | |
|  | |室内光地| | | | |  | |  | | |  | | | | | | | | |
|  | |精装修展位| | | | |  | |  | | |  | | | | | | | | |
|  | |标准展位| | | | |  | |  | | |  | | | | | | | | |
|  | 展位费合计（元） | | | |  | | | | | | | | | | | | | |
|  | 选中展位号填写／ | | | |  | | | | | | | | | | | | | |
|  | 技术交流 | | | | | | | | | | | | | | | | | |
| 收款账号 |  | |  | |  | | | | |  | 时间 | | | | 参展商价格 | | 非参展商价格 | | | 预订场次 | | | | | | | | |
| 收款单位 | **京尚国际会展有限公司** | | | | | | | | |  | 25分钟/场 | | | | 10000元 | | 12000元 | | |  | | | | | | | | |
| 开户行 | **中国银行北京石景山区支行** | | | | | | | | |  | 场次需求： | | | |  | | | | | | | | | | | | | |
| 银行账号 | **3181 7108 4191** | | | | | | | | |  |  | | | |  | | | | | | | | | | | | | |
| 2023**第十七届北京国际半导体展览会（CIOE Expo）** | | | | | | | | | |  | 参展商确认\* | | | | | | | | | | | | | | | | | |
| 地 址：北京市石景山区八角南路65号融科创意中心16层 | | | | | | | | | |  | 我公司已详细了解展会相关要求，并确定申请展位。 | | | | | | | | |  | | | | | | |  |
| 电子邮件：hjz@jingheexpo.com 邮 编：100043 | | | | | | | | | |  | 参展单位盖章 | | | | | | | | |
| 网 站：www.cioe.cc | | | | | | | | | |  |
| 联 系 人：胡京18500732017同微信 | | | | | | | | | |  |
| 电 话：010-88808892 | | | | | | | | | |  |
| 传 真：010-68683796 | | | | | | | | | |  | 负责人签字\* | | |  | | | | | |  | | | |  | | | | |
| 负责人签字 |  | |  | | 主办单位盖章处 | | | | |  | 日期\* | | |  | | | | | |  | | | |  | | | | |